

L Number	Hits	Search Text	DB	Time stamp
-	2	6195878.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/21 08:56
-	9	microcircuit and stackable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:06
-	3	microcircuit and stackable and (361/743, 257/E23.063 , 257/E25.023 , 29/830 , 29/840 , 29/841, 361/735 , 361/746).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:11
-	5	microcircuit and stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:12
-	1	microcircuit same stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:12
-	8427	microcircuit adj1\$ stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:13
-	0	microcircuit adj stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:12
-	827994	microcircuit adj\$3 stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:13

-	8267	microcircuit adj1\$ stackable and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls. and 29/830.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:13
-	8266	microcircuit adj1\$ stackable and PEM and I/O near pad and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:14
-	8266	microcircuit adj1\$ stackable and PEM and " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803 , 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:14
-	8266	microcircuit adj1\$ stackable and PEM same " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:15
-	0	microcircuit near stackable and PEM same " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:15
-	0	microcircuit and PEM same " I/O near pad" and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:15
-	1	microcircuit and PEM and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:15

-	19	microcircuit and encapsulate\$3 and (361/735, 257/685 , 257/686 , 257/723 , 257/777 , 257/E25.011, 361/733 , 361/744 , 361/761 , 361/764 , 361/790 , 361/803, 439/66 , 439/91).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:27
-	9	("4574331" "4581675" "4764846" "5007841" "5027191" "5043794" "5241456" "5376825" "5432681").PN.	USPAT	2003/11/25 09:18
-	398	29/855.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 09:28
-	0	microcircuit and encapsulant and IC and pads and 29/855.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 10:43
-	21	microcircuit and encapsulant and bare same die and pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 11:18
-	19	("4462534" "5024372" "5220200" "5261593" "5293067" "5346861" "5381848" "5388327" "5455390" "5504277" "5539153" "5541460" "5547740" "5564617" "5604379" "5608262" "5701032" "5736456" "5814894").PN.	USPAT	2003/11/25 10:45
-	10	("4989063" "5442240" "5450283" "5497033" "5554887" "5641996" "5650593" "5656863" "5677566" "5684330").PN.	USPAT	2003/11/25 10:49
-	12	("5136366" "5239198" "5289346" "5293072" "5341564" "5355283" "5362679" "5397921" "5420460" "5442231" "5442233" "5519251").PN.	USPAT	2003/11/25 11:05
-	10	("3969813" "4012832" "5424254" "5436202" "5696033" "5700697" "6054012" "6335629" "6358852" "6368886").PN.	USPAT	2003/11/25 11:13
-	23	("H001379" "3482419" "3627901" "3762039" "3969813" "4089704" "4359360" "4384917" "4474621" "4567006" "4691225" "4768286" "4914813" "4980019" "5041396" "5138430" "5149662" "5155068" "5180093" "5252179" "5398926" "5406117" "5424254").PN.	USPAT	2003/11/25 11:17

-	0	microcircuit and encapsulant and bare same die and pads and peter near vo .XP.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 11:19
-	2	microcircuit and encapsulant and bare same die and pads and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 11:20
-	2	5424154.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 12:48
-	2	5424254.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 12:50
-	1	1995-223702.NRAN.	DERWENT	2003/11/25 12:48
-	4	bare same semiconductor near chip and plastic adj package and recovering	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:01
-	0	20020048825.URPN.	USPAT	2003/11/25 12:52
-	10	("3969813" "4012832" "5424254" "5436202" "5696033" "5700697" "6054012" "6335629" "6358852" "6368886").PN.	USPAT	2003/11/25 12:53
-	31	("3969813" "4043080" "4063542" "4089704" "4213698" "4344809" "4359360" "4384917" "4822441" "4826556" "4992135" "5193314" "5223083" "5252179" "5271798" "5291693" "5443675" "5479108" "5585675" "5611876" "5703493" "5750423" "5766496" "5783098" "5792305" "5855727" "5915370" "5932061" "5964646" "6033933" "6055976").PN.	USPAT	2003/11/25 12:54
-	20	5424254.URPN.	USPAT	2003/11/25 12:55
-	1	bare same semiconductor near chip and plastic adj package and I/O near pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:03

-	1	providing adj plastic near package and I/O near pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:04
-	1	providing adj plastic near package and I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:04
-	1	providing adj plastic same package and I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:04
-	19	providing adj plastic same package and pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:07
-	3	providing adj plastic same package and modifying	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:10
-	29	providing adj plastic same package and modification	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/25 13:10